

In The Claims:

Claim 1. (original) A low-lead-content plating process, comprising:
providing an anode;
providing a cathode; and
providing a plating bath containing a plating liquid, wherein the plating liquid includes a pure tin plating liquid, iron ions, thallium ions and lead ions, with the concentrations of lead ions of 2.5 to 10,000 mg/l, thallium ions of 1 to 550 mg/l, and iron ions of 1 to 550 mg/l.

Claim 2. (original) The process of claim 1, wherein the plating liquid further comprising
a brightener;
a methane sulfoante solution; and
a deioned water;
wherein the concentration of the brightener is in the range of 50 to 250 mg/l, and the concentration of the methane sulfonate solution is in the range of 80 to 250 mg/l.

Claim 3. (original) The process of claim 1, wherein the plating process is combined with a barrel plating, the rack plating, a PCB plating, a strip-to-strip plating or a reel-to-reel plating.

Claim 4. (original) The process of the claim 3, wherein the plating process is combined with the barrel plating, the rack plating, the PCB plating, the strip-to-strip plating or the reel-to-reel plating by using a barrel plater, a rack plater, a PCB plater, a strip-to-strip plater or a reel-to-reel plater.

Claims 5-9 (canceled)

No new matter has been added to the application by the amendments made to the claims.

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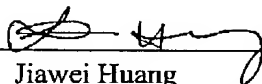
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Respectfully submitted,

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